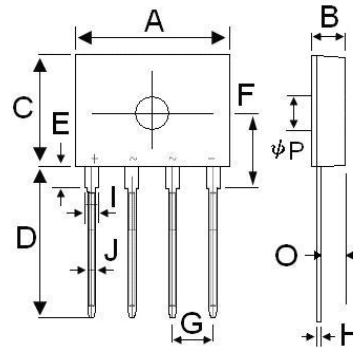


### D3K

### Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ Idea for printed circuit board
- ◆ Glass passivated Junction chip
- ◆ Low reverse leakage
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed  
250°C/10 seconds at terminals



D3K		
Dim.	Min.	Max.
A	14.2	14.7
B	3.30	3.60
C	10.2	10.6
D	13.8	14.4
E	1.8	2.2
F	6.65	7.25
G	3.71	3.91
H	0.35	0.55
I	1.22	1.42
J	0.76	0.86
O	1.8	2.4
P	2.9Φ	3.2Φ
All Dimensions in millimeter		

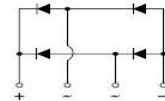
### Mechanical Data

**Case :** Molded plastic body

**Terminals :** Solder plated, solderable per MIL-STD-750,Method 2026

**Polarity :** Polarity symbol marking on body

**Mounting Position :** Any



### Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	UG2K B05G	UG2K B10G	UG2K B20G	UG2K B40G	UG2K B60G	UG2K B80G	UG2KB 100G	UNITS
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum average forward rectified current with heatsink	$I_{(AV)}$	2.0							A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	$I_{FSM}$	60.0							A
Rating for fusing ( $t=8.3ms, T_A=25^\circ C$ )	$I_t^2$	14.94							$A^2s$
Maximum instantaneous forward voltage at 2.0A	$V_F$	1.10							V
Maximum DC reverse current $T_A = 25^\circ C$ at rated DC blocking voltage $T_A = 125^\circ C$	$I_R$	5.0 500							$\mu A$
Typical junction capacitance (Note 1)	$C_J$	30.0							pF
Typical thermal resistance	$R_{\theta JA}$	55.0							$^\circ C/W$
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to +150							$^\circ C$

**Note:** 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

### Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

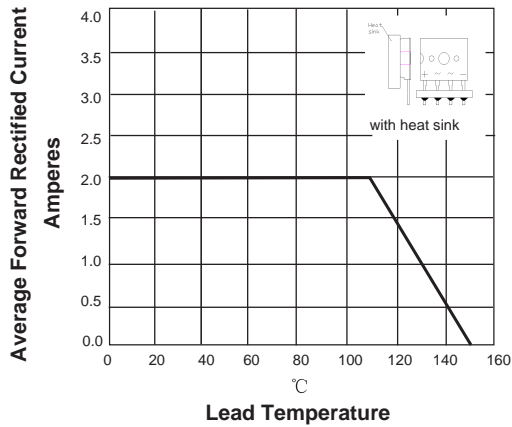


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

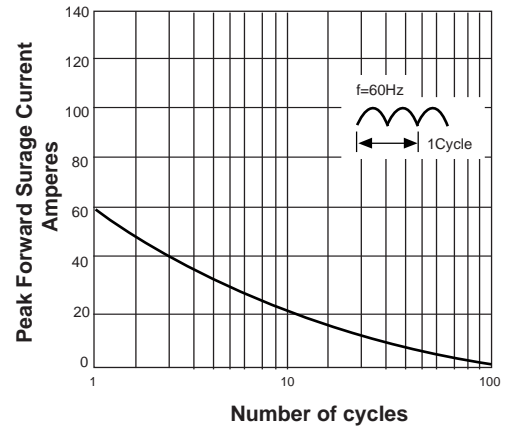


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

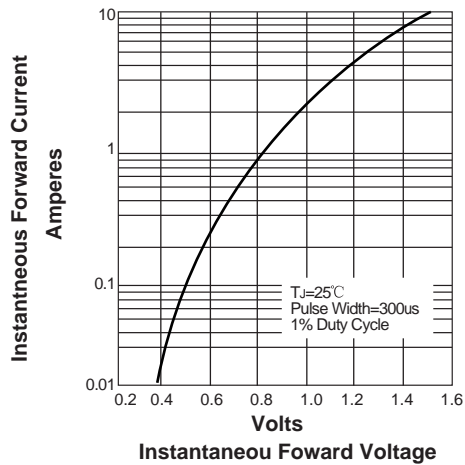
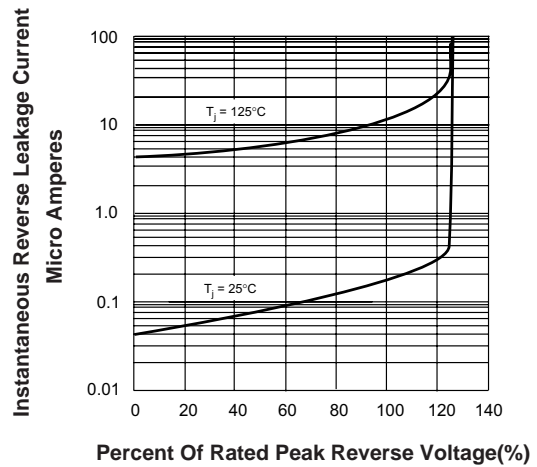
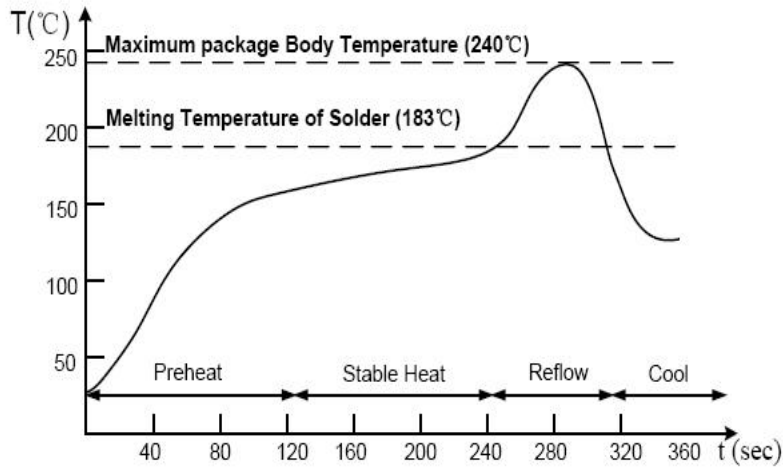


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS



**Suggested Soldering Temperature Profile**



**Note**

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 265°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

**Package Information**

**Tube Package**

Package	Tube (mm)	Q'TY/Tube (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
D3K	445*30.7*5.6	0.03	495*130*70	1.2	520*370*155	6